

Title (en)  
METHOD FOR PRODUCING A DEFORMABLE PRINTED-CIRCUIT SUBSTRATE, AND DEFORMABLE PRINTED-CIRCUIT SUBSTRATE

Title (de)  
VERFAHREN ZUR HERSTELLUNG EINES UMGEFORMTEN SCHALTUNGSTRÄGERS, SOWIE UMGEFORMTER SCHALTUNGSTRÄGER

Title (fr)  
PROCÉDÉ DE FABRICATION D'UN SUPPORT DE CIRCUIT DÉFORMÉ, ET SUPPORT DE CIRCUIT DÉFORMÉ

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Abstract (en)  
[origin: WO2016042414A2] The invention relates to a method for producing a deformable printed-circuit substrate in the form of a laminate consisting of an adhesion promoter film (1), optionally an adhesive layer (2), a printed-circuit film substrate (3) and a purely metallic conductor track (4), the latter having a preferred thickness of the order of magnitude of 1000 atomic layers. The invention also relates to a deformable printed-circuit substrate (1-4). In the method according to the invention, the printed-circuit substrate (1-4) is shaped by means of a gaseous pressure medium, at a temperature above the glass transition temperature and below the melting temperature of the printed-circuit film substrate (3) being shaped, under a sudden, high gas pressure. Thanks to the invention, sharply deformed printed-circuit substrates, in particular freely or spherically shaped printed-circuit substrates can be produced, even with purely metallic conductor tracks. Optional back-moulding (9) and application of decorative layers (11) and/or coating layers (10) allow producing multifunctional, seamlessly and freely shaped plastic components with integrated electronic elements.

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